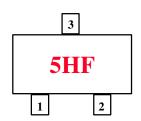


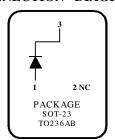
MMBD701

PACKAGE

SOT-23 TO-236AB (Low)



CONNECTION DIAGRAM



Schottky Barrier Diode

Sourced from Process GE

Absolute Maximum Ratings* TA = 25°C unless otherwise noted

Sym	Parameter	Value	Units
T _{stg}	Storage Temperature	-55 to +150	°C
TJ	Operating Junction Temperature	-55 to +125	оС
W _{iv}	Working Inverse Voltage	35	V
P _F	Forward Power Dissipation @ T _A = 25°C	200	mW
	Derate above 25 ^o C	2.0	Mw/°C

^{*}These ratings are limiting values above which the serviceability of any semiconductor device may be impaired

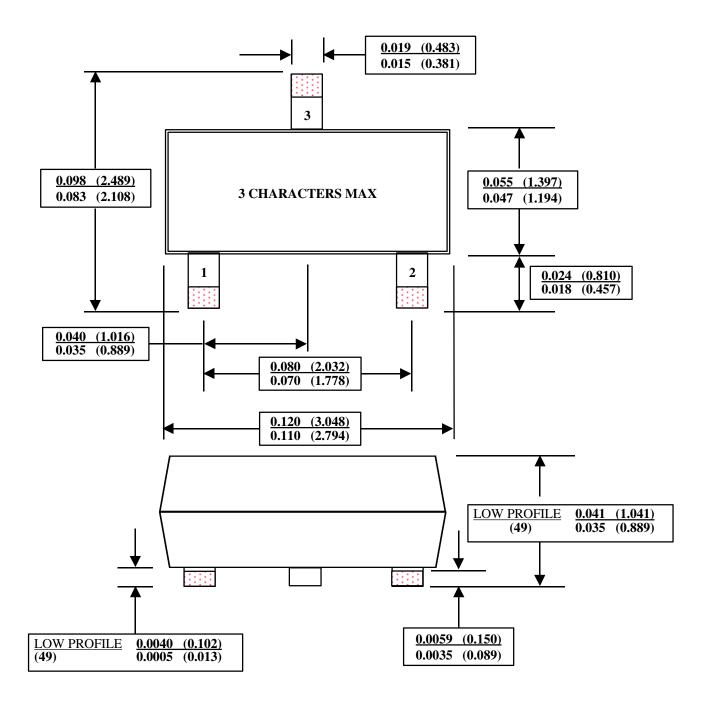
ADVANCED INFORMATION ONLY NOT IN PRODUCTION

Electrical Characteristics TA = 25°C unless otherwise noted

SYM	CHARACTERISTICS	MIN	MAX	UNITS	TEST CONDITIONS
B _V Breakdown Voltage		70		V	$I_R = 10 \text{ uA}$
I _R Reverse Leakage			200	nA	V _R = 35 V
V _F Forward Voltage			500 1.0	mV V	$I_F = 1.0 \text{ mA}$ $I_F = 10 \text{ mA}$
C _⊤ Capacitance			1.0	pF	$V_R = 20 V$ f = 1.0 MHz

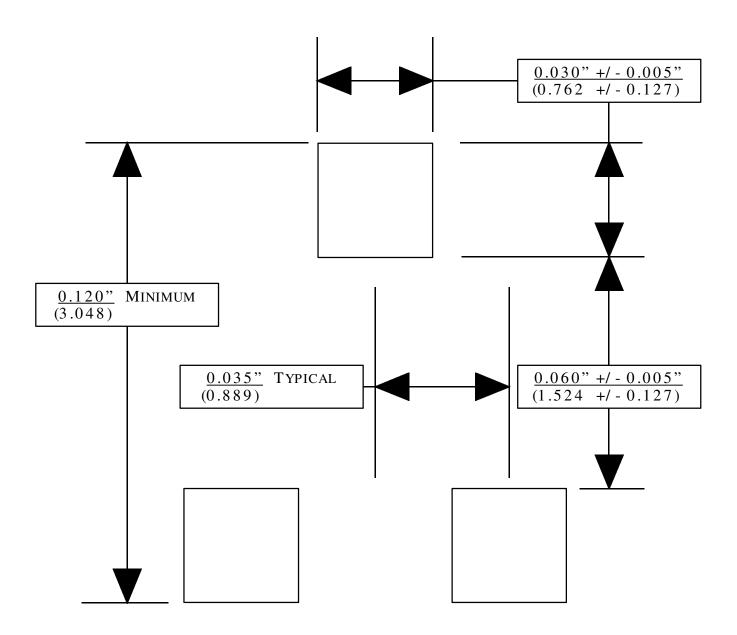
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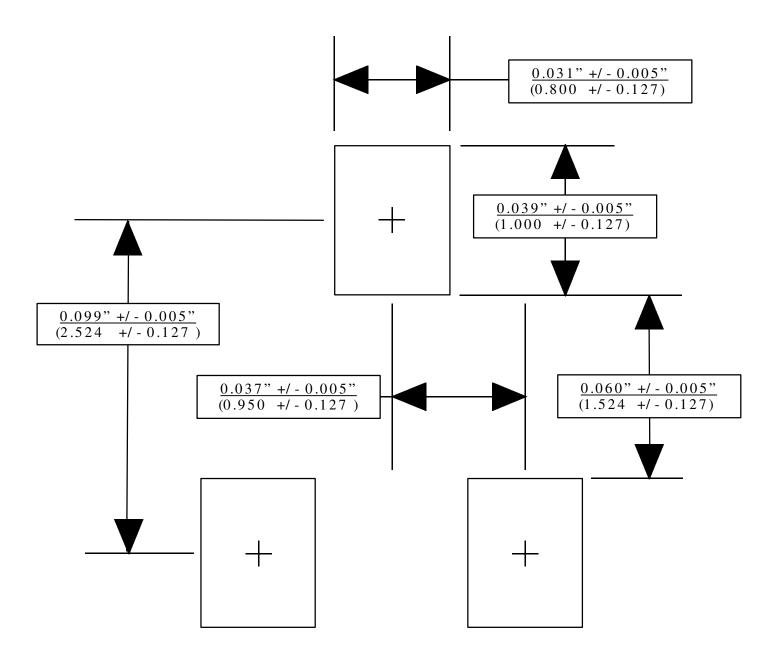






RECOMMENDED SOLDER PADS FOR SOT-23





RECOMMENDED SOLDER PADS FOR U.S. & European SOT-23 & Japanese SC-59

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FACT Quiet Series™ OPTOLOGIC™ Stealth™

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

Datasheet Identification	Product Status	Definition
Advance Information	Formative or In Design	This datasheet contains the design specifications for product development. Specifications may change in any manner without notice.
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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.